



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



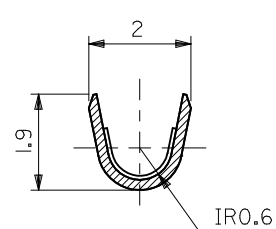
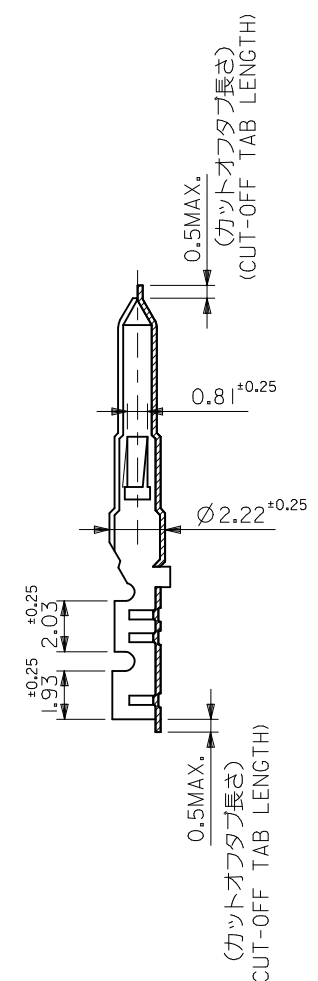
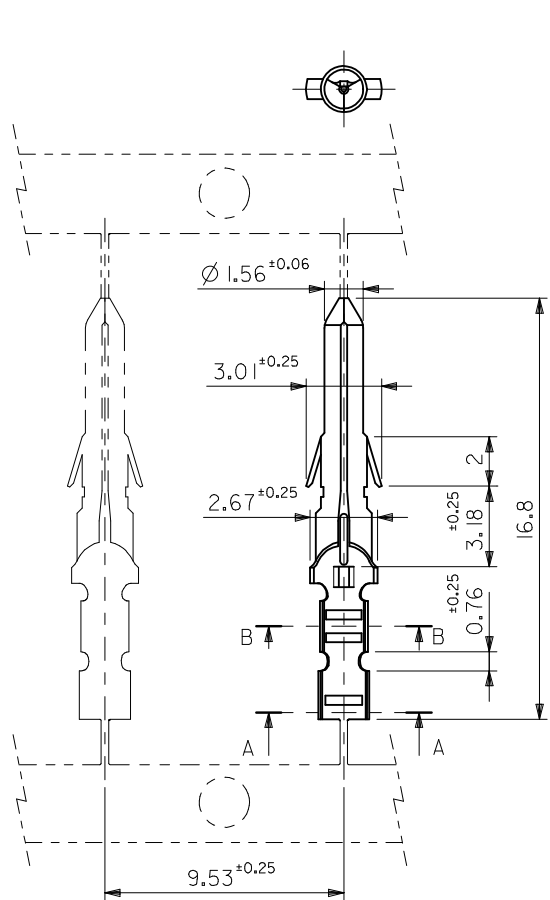
Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

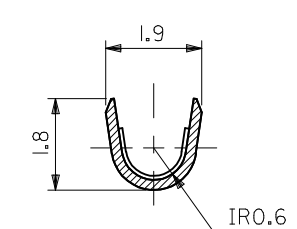
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





SECT. A-A
(SCALE 10 : 1)



SECT. B-B
(SCALE 10 : 1)

注記 NOTES:
1. 一般公差 : ±0.4
GENERAL TOLERANCES: ±0.4

材料 MATERIAL 黄銅 BRASS 0.2 t
仕上げ FINISH —
適用電線範囲 WIRE RANGE AWG#22-#28
被覆外径 INS. RANGE φ 1.1~1.5

REVISED EC NO.: J2017-0317 DRAWINGS CHKD: APPR: MSASAO 2017/03/06 2017/03/15	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	
	0.25 UNDER	±0.03	DRAWN BY	DATE
	0.25 OVER 0.5 UNDER	±0.05	H.HASEGAWA	1993/07/09
	0.5 OVER 0 UNDER	±0.1	CHECKED BY	DATE
	0 OVER 10 UNDER	±0.2	H.HIRAMOTO	1993/07/09
10 OVER 30 UNDER	±0.25	APPROVED BY	DATE	
30 OVER	±0.3	M.FUKUSHIMA	1993/07/09	
ANGULAR	±3 °	MATERIAL NO.		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	

ニッケル (2 μm MIN.) 下地 金 (0.35 μm MIN.) GOLD (0.35 μm MIN.) OVER NICKEL (2 μm MIN.)	39-00-0337	I854GL	バラ端子 LOOSE
銅 (0.5 μm MIN.) 下地 錫 (0.9 μm MIN.) TIN (0.9 μm MIN.) OVER COPPER (0.5 μm MIN.)	39-00-0335	I854TL	バラ端子 LOOSE
	39-00-0280	I854T	連鎖端子 CHAIN
メッキ PLATING	EDP.NO.	ENG.NO.	形状 FORM

SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
TITLE 0.62 DIA CRIMP MALE TERM		
molex		
DOCUMENT NO. SD-1854*	SHEET NO. 1 OF 1	